

Packaging's Role in RF and Micro-Electronics

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Abstract

Often overlooked, packaging can and often does have significant impact on the performance of RF and Microelectronics. We will review how packaging can help protect against not only ESD damage but also EOS, caused by corrosion and oxidation of components. Corrosion can lead to increased resistance and contamination by packaging can impact performance characteristics. We will compare and contrast various packaging methods, materials and schemes, looking at benefits and drawbacks.